

# PK03003\_PGC2KL\_UWG49

(V1.8)

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# **Revisions History**

### **Document Revisions**

Version	Date of Release	Revisions
V1.8	25.12.2020	Initial release

(V1.8) 1/15



# **About this Manual**

#### **Terms and Abbreviations**

Terms and Abbreviations	Meaning	
POD	Package Outline Drawing	
WLCSP	Wafer Level Chip Scale Packaging	

(V1.8) 2/15



# **Table of Contents**

Revisions History	1
About this Manual	
Table of Contents	3
Tables	4
Figures	5
Chapter 1 Introduction to Packaging	6
Chapter 2 Package Dimension and Pins	7
2.1 Package Outline Dimension	7
2.2 Pin Description	8
2.2.1 Pinout Diagram	11
2.2.2 IO Banks	
2.2.3 Power and GND Placement	12
2.2.4 Pin Name List	12
Disclaimer	15



# **Tables**

Table 2-1 Dimensional Data	7
Table 2-2 Product Pin Definitions	8
Table 2-3 Pin Name List	12

(V1.8) 4 / 15



# **Figures**

Figure 2-1 Package Outline Dimension (POD)	7
Figure 2-2 Pinout Diagram	11
Figure 2-3 IO Banks	12
Figure 2-4 Power and GND Placement	12

(V1.8) 5 / 15



## **Chapter 1 Introduction to Packaging**

The PGC2KL-UWG49 device is packaged with WLCSP wafer-level chip. Its package size is 3.189x3.052mm, with 49 solder balls, a pitch of 0.4mm between the balls and a maximum package thickness of 0.595mm.

(V1.8) 6/15



### **Chapter 2 Package Dimension and Pins**

### 2.1 Package Outline Dimension

Table 2-1 Dimensional Data

Unit: mm

Dimension	Values			Dimension	Values		
Symbols	Symbols Min. Typ. Max. Symbols	Symbols	Min.	Тур.	Max.		
D	3.032	3.052	3.072	A	0.485	0.540	0.595
D1	-	2.4	-	A1	0.157	0.175	0.193
Е	3.169	3.189	3.209	A2	0.340	0.365	0.390
E1	-	2.4	-	е	-	0.4	-
b	0.207	0.230	0.253				

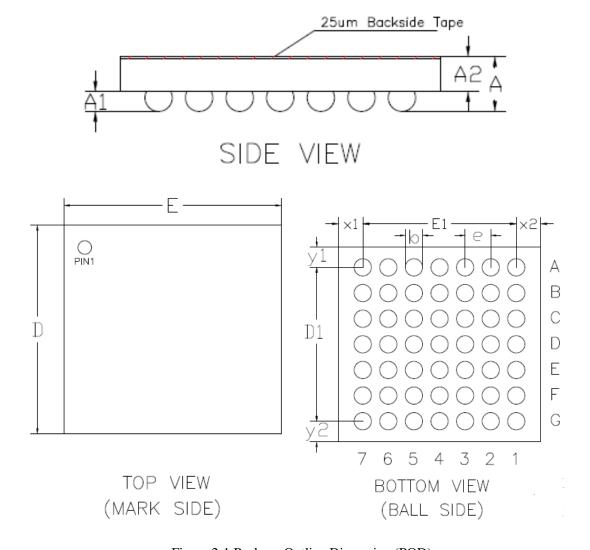


Figure 2-1 Package Outline Dimension (POD)

(V1.8) 7/15



### 2.2 Pin Description

The PGC2KL-UWG49 device has 39 user I/Os.

Table 2-2 Product Pin Definitions

Pin Name	Pin Type	Direction	Pin Description
User I/O Pin			
DIFF[I,IO]_XX_NN[P, N]	User pin	Input/Out put	User I/O.  (1) DIFFI indicates support for differential signal input and pseudo-differential output; DIFFIO indicates support for differential signal input and true differential output, which can be used for transmitting and receiving LVDS signals;  (2) "XX" denotes the Bank number, with possible values being B0, B1, B2, B3, B4, and B5;  (3) "NN" denotes the sequence number of the programmable I/O group within the Bank, starting from 0 and increasing incrementally;  (4) [P,N]: "P" denotes the positive side of the differential pair, and "N" denotes the negative side; During power-up, the user I/O is at a low voltage;  After power-up is complete but before configuration, the general user I/O is at pull-down status;  During configuration, the user I/O is at pull-down status;
Configuration <sup>1</sup>			
INIT_FLAG_N	Multi-func tion pin	Bi-Directi onal (Open-dra in)	Configurable multiplexed pin, with an internal weak pull-up resistor. When used as a configuration pin: During power-up, it is at a low voltage; After power-up is complete before configuration, it is open-drain at weak pull-up status; During configuration, it is open-drain at weak pull-up status; During initialization, the pin can be driven to a low voltage by an external input to indicate an error or to delay configuration. During configuration, the pin serves as an indicator output for configuration errors, where a low voltage indicates an error has occurred;
CFG_DONE	Multi-func tion pin	Bi-Directi onal (Open-dra in)	Configurable multiplexed pin, with an internal weak pull-up resistor. When it is used as configuration pin, it serves as an indicator output for configuration completion, where a high voltage indicates configuration is complete; Before or during configuration, the pin is driven to a low voltage; after configuration is complete, the pin can continue to be driven to a low voltage by an external source. If the internal start-up timing detects CFG_DONE at a low voltage, the internal start-up circuitry maintains its state until CFG_DONE goes high to continue the start-up process;
RSTN	Multi-func tion pin	Input	Configurable multiplexed reset pin, with an internal weak pull-up resistor. When it is used as a reset pin, it serves to restart the configuration process, active low. At this situation, it must be pulled up with an external resistor (internal weak pull-up resistor typically has a value of over 20kOhms, with a relatively weak pull-up strength); when the pin is at a low voltage, the CPLD enters reset state, with all I/Os in a weak pull-down status;

(V1.8) 8 / 15



Din Nama	Din Tema	Dimostica	Din Description
Pin Name	Pin Type	Direction	Pin Description  Configurable multipleved clock pin with an internal
CFG_CLK	Multi-function pin	Input/Out put	Configurable multiplexed clock pin, with an internal weak pull-up resistor. When it is used as a configuration pin:  In slave SPI configuration mode, the pin serves as a clock input to acquire configuration data from an external source;  In master SPI configuration mode, the pin serves as a clock output to acquire configuration data from an external source; in this mode, a 1kOhms pull-up resistor is needed;  Master SPI mode and slave SPI mode are allowed to be enabled simultaneously, but using them at the same time is not permitted;
TCK	Multi-func tion pin	Input	Multiplexed JTAG test clock input pin; requires an external 4.7kOhms pull-down resistor;
TMS	Multi-func tion pin	Input	Multiplexed JTAG test mode select input pin; with an internal weak pull-up resistor, pulled up to VCCIO0;
TDI	Multi-func tion pin	Input	Multiplexed JTAG test data input pin; with an internal weak pull-up resistor, pulled up to VCCIO0;
TDO	Multi-func tion pin	Output	Multiplexed JTAG test data output pin; with an internal weak pull-up resistor, pulled up to VCCIO0.
JTAGEN	Multi-func tion pin	Input	Optional JTAG port behaviour control pin, usually used in user mode, when JTAG pins are configured as configuration I/Os, this pin is user I/O, with the state controlled by the user; when JTAG pins serve as user I/Os, JTAGEN serves as a dedicated input used to control the availability of JTAG pins; the default state is weak pull-down; when JTAGEN is configured as a dedicated I/O: (1) When at a low voltage, the JTAG pins function as user I/Os; (2) When at a high voltage, the JTAG pins function as JTAG configuration port.
FCS_N	Multi-func tion pin	Output	Configurable multiplexed pin, used for master SPI configuration mode,  (1) In master SPI mode, outputs an active-low chip select signal to an external Flash;  (2) After configuration is completed, it can be used as a user I/O.
MISO_SO	Multi-function pin	Input/Out put	Configurable multiplexed pin; (1) MISO, serial data input in master SPI mode; (2) SO, serial data output in slave SPI mode; Master and slave SPI modes are allowed to be enabled simultaneously, but using them at the same time is not permitted.
MOSI_SI	Multi-function pin	Input/Out put	Configurable multiplexed pin; (1) MOSI, serial data output in master SPI mode; (2) SI, serial data input in slave SPI mode; Master and slave SPI modes are allowed to be enabled simultaneously, but using them at the same time is not permitted.
FCSI_N	Multi-func tion pin	Input	Configurable multiplexed pin, with an internal weak

(V1.8) 9 / 15



Pin Name	Pin Type	Direction	Pin Description
			pull-up resistor;
			In slave SPI mode, active-low chip select input.
	Multi-func	Input	Configurable multiplexed pin, clock input in slave I2C
SCL	tion pin	(Open-dra in)	mode; requires an external weak pull-up resistor.
SDA	Multi-func tion pin	Bi-Directi onal (Open-dra in)	Configurable multiplexed pin, data input/output in I2C mode; requires an external weak pull-up resistor.
SPAL_CLK	Multi-func tion pin	Input	Clock input in slave parallel X16 configuration mode.
SPAL_CS_N	Multi-func tion pin	Input	Chip select input in slave parallel X16 configuration mode. Active-low
SPAL_RDWR_N	Multi-func tion pin	Input	Read/write control input in slave parallel X16 configuration mode; 1: read; 0: write.
SPAL_BUSY	Multi-func tion pin	Output	Busy indicator in slave parallel X16 configuration mode; During readback, if the data is not ready, SPAL_BUSY changes to high voltage.
SPAL_D15~SPAL_D0	Multi-func tion pin	Input/Out put	Data bus in slave parallel X16 configuration mode.
Clock, PLL	<u> </u>		
CLK[0,1,2][P,N]_[B0, B1,,B5]	Multi-func tion pin	Input	Global clock input pin; can also be used as user I/O; (1) [0,1,2]: clock pin numbers; (2) [P,N]: positive and negative sides of the differential clock pins; (3) [B0,B1,,B5]: bank numbers.
PLL[0,1]_CLKIN_[P, N]	Multi-func tion pin	Input	PLL input. PLL can choose to directly input a clock from these pins; they can also be used as user I/Os; (1) [0,1]: corresponds to PLL0 and PLL1; (2) [P,N]: positive and negative sides of the differential clock pins.
PLL[0,1]_CLKFB_[P, N]	Multi-func tion pin	Input	Optional PLL feedback clock input. PLL can select to feedback clock externally from these pins; they can also be used as user I/Os; (1) [0,1]: corresponds to PLL0 and PLL1; (2) [P,N]: positive and negative sides of the differential clock pins.
Power			
VCC		Power	External power supply of 1.2V, providing power to the core logic.
VCCIO[0,2,5]		Power	I/O Bank power.
VSS		Ground	Ground associated with VCC;
MIPI_CTRL	Dedicated		MIPI high-performance application control pin; when connected to 2.5V or 3.3V, the device supports high-performance MIPI transmission functions; when connected to VSS or left floating, the device does not support the high-performance MIPI transmission capabilities.

Note:

1. When the configured multiplexed pin is used as a user I/O, its status is the same as the user I/O pin.

(V1.8) 10 / 15



### 2.2.1 Pinout Diagram

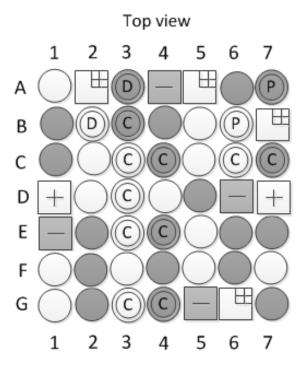


Figure 2-2 Pinout Diagram

Note: the Pinout symbols have the following meanings:

		COMP(N) TRUE(P)
General IO	DIFFIO*	
	DIFFIO*/D0~D31	(D) (D)
Multiplex IO	DIFFIO*/CLK*	© ©
,	DIFFIO*/PLL*	PP
	VSS	
Power , Ground	vcc	+
	VCCIO	

(V1.8) 11/15



#### 2.2.2 IO Banks

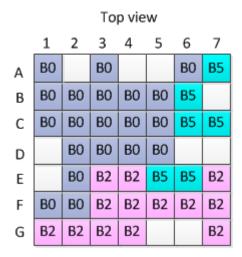


Figure 2-3 IO Banks

#### 2.2.3 Power and GND Placement

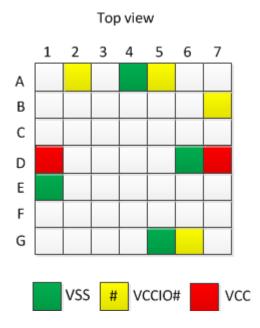


Figure 2-4 Power and GND Placement

#### 2.2.4 Pin Name List

Table 2-3 Pin Name List

Bank Name	Pin Name	Pin Number	Differential Pair
B0	DIFFI_B0_0N/CFG_DONE	A1	IO_1_N
В0	DIFFI_B0_0P/INIT_FLAG_N	B1	IO_1_P

(V1.8) 12 / 15



Bank Name	Pin Name	Pin Number	Differential Pair
B0	DIFFIO_B0_1N/SPAL_CLK	D2	IO_2_N
B0	DIFFIO_B0_1P/SPAL_CS_N	C1	IO_2_P
B0	DIFFIO_B0_3N/SPAL_RDWR_N	C2	IO_4_N
B0	DIFFIO_B0_3P/SPAL_BUSY	E2	IO_4_P
B0	DIFFI_B0_8N/RSTN	F1	IO_9_N
B0	DIFFI_B0_8P/JTAGEN	F2	IO_9_P
B0	DIFFIO_B0_9N/SPAL_D7	B2	IO_10_N
B0	DIFFIO_B0_9P/SPAL_D6	A3	IO_10_P
B0	DIFFI_B0_12N/SDA/CLK0N_B0	C3	IO_13_N
B0	DIFFI_B0_12P/SCL/CLK0P_B0	В3	IO_13_P
B0	DIFFIO_B0_15N/CLK1N_B0	D3	IO_16_N
B0	DIFFIO_B0_15P/CLK1P_B0	C4	IO_16_P
B0	DIFFI_B0_16N/TMS	B5	IO_17_N
B0	DIFFI_B0_16P/TCK	B4	IO_17_P
B0	DIFFI_B0_20N/TDI	C5	IO_21_N
B0	DIFFI_B0_20P/TDO	A6	IO_21_P
B0	DIFFIO_B0_25N	D4	IO_26_N
B0	DIFFIO_B0_25P	D5	IO_26_P
B2	DIFFI_B2_1N/MOSI_SI	G1	IO_56_N
B2	DIFFI_B2_1P/FCSI_N	G2	IO_56_P
B2	DIFFI_B2_13N/CLK1N_B2	G3	IO_68_N
B2	DIFFI_B2_13P/CLK1P_B2	G4	IO_68_P
B2	DIFFI_B2_15N	F3	IO_70_N
B2	DIFFI_B2_15P	F4	IO_70_P
B2	DIFFI_B2_17N/CLK0N_B2	E3	IO_72_N
B2	DIFFI_B2_17P/CLK0P_B2	E4	IO_72_P
B2	DIFFI_B2_21N/MISO_SO	F5	IO_76_N
B2	DIFFI_B2_21P/CFG_CLK	F6	IO_76_P
B2	DIFFI_B2_25P/FCS_N	G7	IO_80_P
B2	DIFFI_B2_27N	F7	IO_82_N
B2	DIFFI_B2_27P	E7	IO_82_P
B5	DIFFI_B5_2P/PLL0_CLKIN_P	A7	IO_101_P
B5	DIFFI_B5_2N/PLL0_CLKIN_N	B6	IO_101_N
B5	DIFFI_B5_4P/CLK0P_B5	C7	IO_103_P
B5	DIFFI_B5_4N/CLK0N_B5	C6	IO_103_N
B5	DIFFI_B5_8P	E6	IO_107_P
B5	DIFFI_B5_8N	E5	IO_107_N
	VCC	D1	
	VCC	D7	

(V1.8) 13 / 15



Bank Name	Pin Name	Pin Number	Differential Pair
	MIPI_CTRL	A4	
	VCCIO0	A2	
	VCCIO0	A5	
	VCCIO2	G6	
	VCCIO5	В7	
	VSS	D6	
	VSS	E1	
	VSS	G5	

(V1.8) 14/15



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(V1.8) 15 / 15